

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yao-Chun Chuang</td> <td>01/02/2013</td> </tr> <tr> <td>Chita Chuang</td> <td>01/02/2013</td> </tr> <tr> <td>Ming Hung Tseng</td> <td>01/02/2013</td> </tr> <tr> <td>Chen-Shien Chen</td> <td>01/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yao-Chun Chuang	01/02/2013	Chita Chuang	01/02/2013	Ming Hung Tseng	01/02/2013	Chen-Shien Chen	01/02/2013
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Yao-Chun Chuang	01/02/2013										
Chita Chuang	01/02/2013										
Ming Hung Tseng	01/02/2013										
Chen-Shien Chen	01/02/2013										
RECEIVING PARTY DATA											
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.										
Street Address:	No. 8, Li-Hsin Rd. 6										
Internal Address:	Science-Based Industrial Park										
City:	Hsin-Chu										
State/Country:	TAIWAN										
Postal Code:	300-77										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13735750</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13735750						
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Application Number:	13735750										
CORRESPONDENCE DATA											
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NAME OF SUBMITTER:	Wendy Saxby										
Total Attachments: 1 source=TSM12_0763_Assignment#page1.tif											

CH \$40.00 13735750

ATTORNEY DOCKET NO.  
TSM12-0763

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan-300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>ELONGATED BUMP STRUCTURES IN PACKAGE STRUCTURE</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Yao-Chun Chuang</i> Yao-Chun Chuang	<i>Chita Chuang</i> Chita Chuang	<i>Ming Hung Tseng</i> Ming Hung Tseng	<i>Ch Shien Chen</i> Chen-Shien Chen
DATE	<i>2013. 1. 2</i>	<i>2013. 1. 2</i>	<i>2013. 1. 2</i>	<i>2013. 1. 2</i>
RESIDENCE (City, County, State)	Hsin-Chu Taiwan	Kaohsiung City Taiwan	Toufen Township Taiwan	Zhubei City Taiwan